Selective Soldering System
ATF Smart-Select35/25

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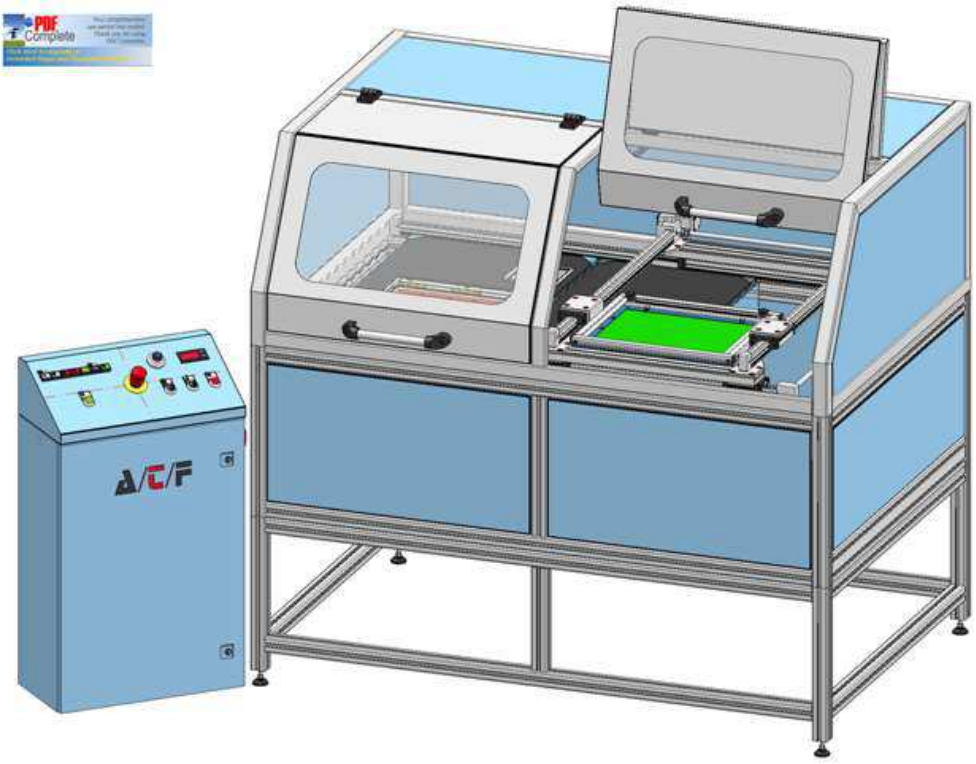


Selective soldering – low price, high performance

Rigid design, easy accessibility and easy maintenance are some of the characteristics of the ATF selective machine. Therefore special attention is paid for the construction of the X/Y motion system. High quality solder results can be achieved only if motion system and solder nozzle are running with minimum of vibration.

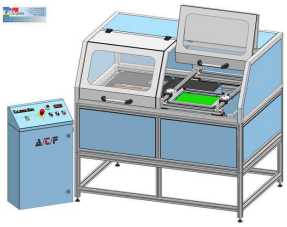
With selective soldering machines it is always important to keep the small nozzle free of dross. Therefore the ducts are designed to reduce significantly the chance of dross clogging the nozzle. As a further improvement of the solder joint and reduction of dross, the use of nitrogen is recommended. Locally at the nozzle nitrogen is applied to have maximum advantage and minium consumption.

The thousand fold aproved ATF IR-preheater is especially designed to provide excess of energy.

The software allows entering all existing X/YZ parameters. The Teach-In-Process allows to select every single solder joint and storing those parameters to the NC-controller.

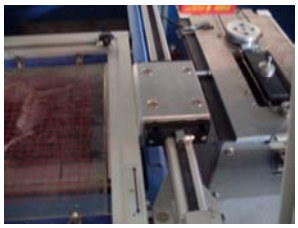
For the solder pot a high-grade stainless steel is used and protected by a ceramic coating to prevent deterioration by high tin content lead-free soldering alloy.

The ATF Smart_Select 35/25 is designed for applications, where machine flexibility and cell manufacturing is required. The ATF Smart-Select offers high performance – and low price



Technical description

Machinery
The welded steel base frame is pre-condition for a long-term reliability. Slighting doors allow easy and fast access to the machine; large windows allow solder process monitoring.



X/Y Motion system

In difference to robot arms is the X-Y-frame of the ATF machine very sturdy and precondition for precise positioning of the PCB on the mini wave. The z-movement is carried out by high precision spindles, which lift the entire solder pot. The heavy set-up avoids oscillations of the table and allow reproducible movement.
Max PCB size 350 x 250 mm.

Fluxer

The **AHP** (Airless-High-Precision) Fluxer ensures well-defined flux distribution.
A high frequency valve controls the volume.

Pre-heating

Thousand fold approved ATF IR preheat ensure s a even spread of heat. The preheater is running in stand by mode and switches on just before the PCB needs warm up.
The emitters are protected by glass to allow easy cleaning.

Solder pot(s)
High-grade stainless steel is used for the solder pot(s). Optional ceramic coating is available for lead-free solder. The ducts, designed by ATF can be removed easily and reduce significantly dross clogging the nozzle. The nozzle(s) can be changed easily. Several diameters are available as standard.

PC control
Easy process monitoring via Note book